Nanometers, Gigahertz, and Femtoseconds

Recent Progress in Field Programmable Gate Arrays

Peter Alfke Xilinx, Inc peter.alfke@xilinx.com



FPGA State of the Art 2004

- 90-nanometer manufacturing technology
- Ten Gigahertz serial I/O (SerDes) in silicon
- 0.07 femtosecond asynchronous data capture window causes 1.5 ns metastable delay



Three Sections:

1. Bird's Eye View of FPGA Technology

2. FPGAs in 2004: Virtex-4 Introduction

3. Special Problems and Solutions

all in 45 minutes...



3 LHC Boston Sept 04 PA

A Bird's Eye View...

Lower Cost

Moore's Law is alive Smaller geometries and larger wafers and lower defect density (=higher yield) continue to achieve lower cost per function LUT + flip-flop: \$1.- in 1990, \$0.002 in 2003 State-of-the-art: 90 nm on 300 mm wafers Spartan-3 uses this technology for lowest cost

Rapid price reductions, intense competition



A Bird's Eye View... **More Logic and Better Features:** >100,000 LUTs & flip-flops >200 BlockRAMs, and same number 18 x 18 multipliers 1156 pins (balls) with >800 GP I/O 50 I/O standards, incl. LVDs with internal termination 16 low-skew global clock lines Multiple clock management circuits On-chip microprocessor(s) and Gbps transceivers Gate count is really a meaningless metric



A Bird's Eye View...

Higher Speed

Smaller and faster transistors

90 nm technology, using 193 nm ultra-violet light Cu interconnect (instead of Al) was easily achieved Low-K dielectric progress is disappointing

System speed: up to 500 MHz,

Mainly through smart interconnects, clock management, dedicated circuits, flexible I/O.

Integrated transceivers running at 10 Gigabits/sec Speeding up general-purpose logic is getting difficult



A Bird's Eye View...

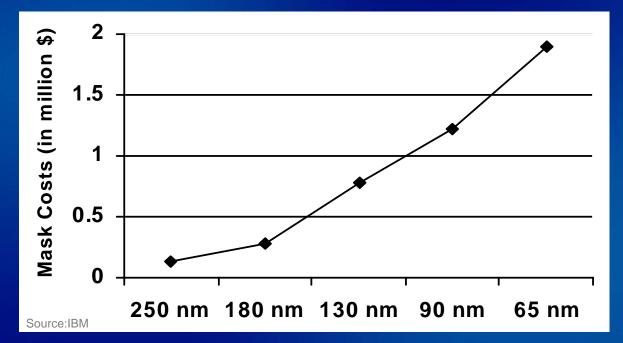
Better tools Back-End Place&Route and XST synthesis VHDL and Verilog becoming entry point IP/Cores speed up design and verification **Embedded** Software Development Tools support architectures and merge HW and SW **Domain-Specific Languages** System Generator bridges the gap between Matlab/Simulink and FPGA circuit description

ASIC-size FPGAs need ASIC-like tools



ASICs Are Losing Ground

Mask set >\$1M + design + verification + risk



ASICS are only for extreme designs: Extreme volume, speed, size, low power



Evolution

	1965	1980	1995	2010(?)
Max Clock Rate (MHz)	1	10	100	1000
Min IC Geometries (µ)	-	5	0.5	0.05
# of IC Metal Layers	1	2	3	12
PC Board Trace Width (µ)	2000	500	100	25
# of PC-Board Layers	1-2	2-4	4-8	10-20

Every 5 years: System speed doubles, IC geometry shrinks 50% Every 7-8 years: PC-board min trace width shrinks 50%



The Ever-Shrinking Circuitry

Number of LUTs + flip-flops + routing that fit on the cross section of a human hair

- 2000 2 LUTs in Virtex-II (150 nm)
- 2002 3 LUTs in Virtex-IIPro (130 nm)
- 2004 4 LUTs in Virtex-4 (90 nm)
- 2005 8 LUTs = one CLB in 65 nm

Moore's law is alive and well in FPGAs



Middle-of-the-Road FPGAs

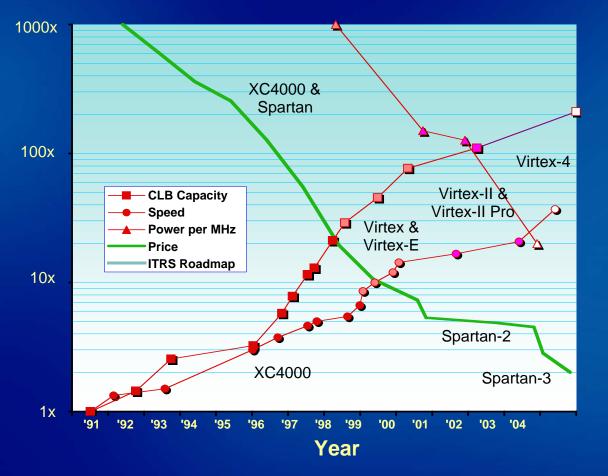
1990	XC3042	288	LUTs + flip-flops
1994	XC4005	512	LUTs + flip-flops
1998	XC4013XL	1,152	LUTs + flip-flops
2000	XCV300	6,144	LUTs + flip-flops
2002	XC2V1000	10,240	LUTs + flip-flops
2004	XC2VP30	27,382	LUTs + flip-flops
2005	XC4V60-LX	53,248	LUTs + flip-flops

Same price for each: One day's engineering salary



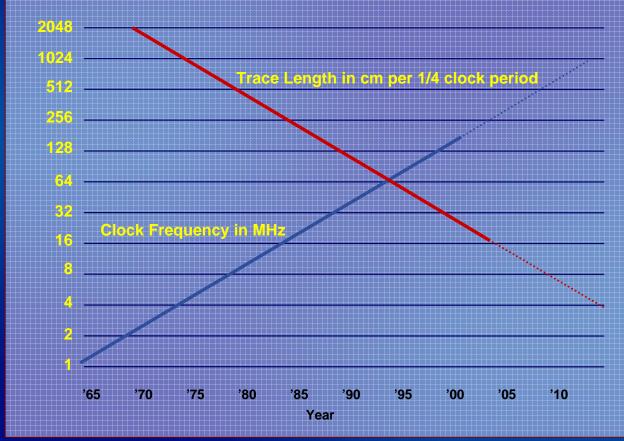
Thirteen Years of Progress

200x More Logic plus memory, µP, DSP, MGT 40x Faster 50x Lower Power per function x MHz 500x Lower Cost per function





Moore Meets Einstein



Speed Doubles Every 5 Years... ...but the speed of light never changes

13 LHC Boston Sept 04 PA

Higher Leakage Current...

High Leakage current = static power consumption Was <100 microamps, now > 100 mA, even amps (!) Caused by:

- Gate leakage due to 16 Å gate thickness
- Sub-threshold leakage current incomplete turn-off because threshold does not scale
 Tyranny of numbers:
 10 nA x 100 million transistors = 1 A evenly distributed, thus no reliability problem
 Sub-100 nm is not ideal for portable designs



FPGAs in 2003

1000 to 80,000 LUTs and flip-flops, millions of bits in dual-ported RAMs
Low-skew Global Clocks, Frequency synthesis, 50 ps phase control
18 Kbit BlockRAMs and 18 x 18 multipliers

FPGAs are not glue-logic anymore



FPGAs in 2003

1000 to 80,000 LUTs and flip-flops, millions of bits in dual-ported RAMs
Low-skew Global Clocks, Frequency synthesis, 50 ps phase control
18 Kbit BlockRAMs and 18 x 18 multipliers

FPGAs are not glue-logic anymore



FPGAs in 2003

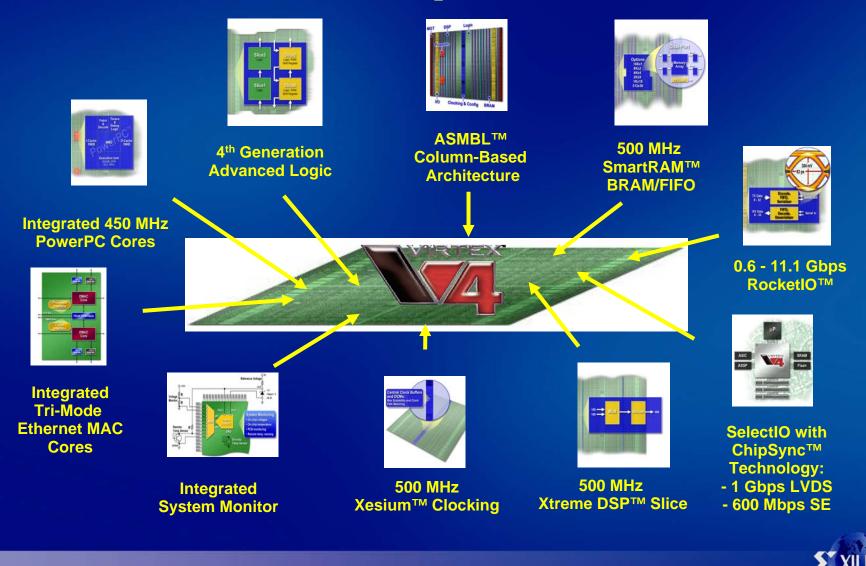
300+ MHz system clock,
800 MHz I/O
3+ Gigabit transceivers
Embedded hard and soft microprocessors
Design security: Triple-DES encryption
VHDL/Verilog entry, synthesis, auto place and route

FPGAs are a compelling alternative to ASICs





Virtex-4 in September 2004

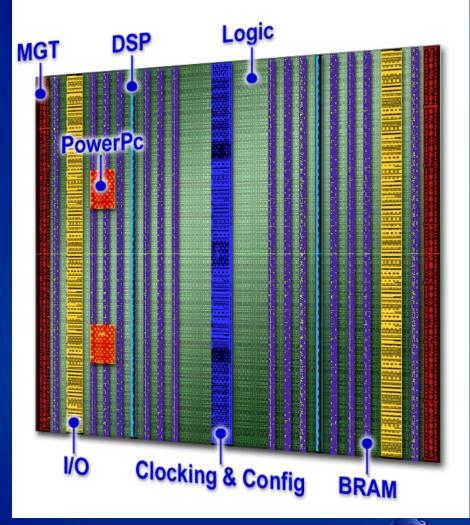


19 LHC Boston Sept 04 PA

New ASMBL[™] Columnar Architecture

Enables "Dial-In" Resource Allocation Mix

- Logic, DSP, BRAM, I/O, MGT, DCM, PowerPC
- Made possible by Flip-Chip Packaging
 - I/O Columns Distributed throughout the Device





90 nm technology, triple-oxide, 1.2-V Vccint supply General-purpose I/O up to 1 Gbps,

Vcco=1.5, 2.5, or 3.3-V

0.6 to 11.2 Gigabit/sec *Rocketl/O* transceivers

Advanced Silicon Modular Block architecture

Three sub-families:

V4-LX for logic-intense applications

V4-SX for DSP-intensive applications

V4-FX with PPC micros and multi-gigabit transceivers

Common architecture for diverse applications



FPGA Innovation: Virtex-4 • Higher Performance: 500 MHz for all sub-blocks More Versatility New innovative functions • Higher Level of Integration More LUTs, flip-flops, RAMs, multipliers Lower Cost Smaller area = lower cost per function Lower Power per (Function times MHz)



Flip-chip packaging: lower pin-inductance, stiffer Vcc distribution
Lower power per function and MHz Triple-oxide gates, multiple thresholds, smaller size, lower Vcc, better design
Better clocking, less skew, more flexibility
Better configuration control, partial reconfiguration
Robust configuration cell, SEU tolerant like 130 nm

Details available now, after Virtex-4 official introduction



Improved I/O Flexibility and Performance Supports >50 standards, on-chip termination Source-synchronous and system-synchronous Serializer/deserializer behind each pin Programmable delay available for each pin > 1Gbps SelectI/O on each pin >10 Gbps transceivers on dedicated pins (-FX family only)

Source-synchronous I/O improves performance Serial I/O saves pins and pc-board area

Faster logic and memory 500+ MHz operation of all on-chip functions
32-bit arithmetic 48-bit adders and synchronous loadable counters
Up to 72-bit wide memory
4- to 36-bit wide FIFO control in each BlockRAM Operates with fully independent write and read clocks Reliable EMPTY and FULL outputs also ALMOST Empty and ALMOST Full

FIFOs need no fabric resources and no design expertise



Advanced Clocking

Proper clocking is extremely important for performance and reliability Most design need many global clock lines with minimal clock delay and clock skew **Digital Clock Manager (DCM) provides:** Four-phase outputs, Frequency multiplication and division Fine phase adjustment



Advanced I/O

>50 Different Output Standards

(strength, voltage, input threshold, etc)
 multiple parallel output transistors
 which are either fully on or fully off,
 Nothing is ever analog, except in LVDS

Digitally Controlled Impedance =DCI for series-termination of transmission-line drivers Adjusts up/down strength to be = external resistor One external pull-up and pull-down resistor per bank V2Pro and Virtex-4 can "update-only-if-necessary"



System Synchronous

- System-Synchronous when the clock arrives "simultaneously" at all chips typically used below 200 MHz clock rate
- On-chip clock distribution DCM
 Zero clock delay controls set-up time, and avoids hold time requirements

The traditional design methodology

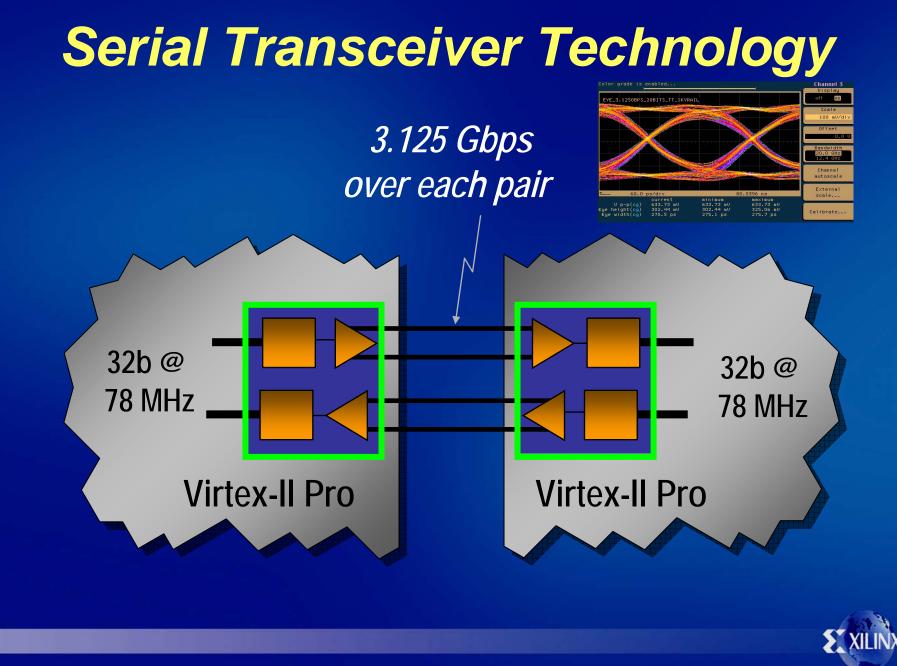


Source Synchronous

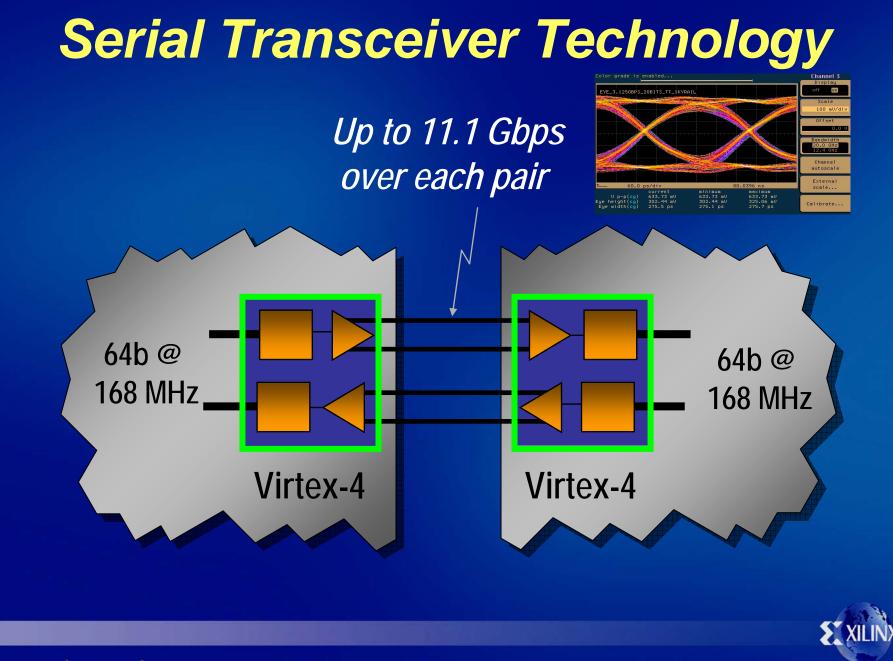
Each data bus has its own clock trace typically used at 200 to 800 MHz clock rate On-chip clock-distribution DCM centers the clock in the data eye Adds more unidirectional-only clock lines

The only way above 300 MHz



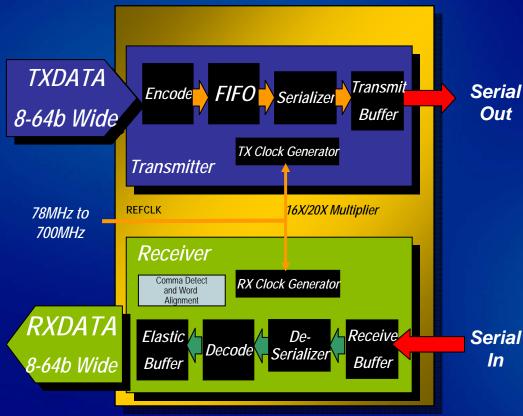


30 LHC Boston Sept 04 PA



31 LHC Boston Sept 04 PA

RocketIO[™] Multi-Gigabit Transceiver



8 to 24 per device

erial 622 Mb/s – 11.1 Gb/s

Programmable Features: 64b/66b or 8b/10b EnDec Comma Detect Rx and Tx FIFO Pre-Emphasis Receiver Equalization Output Swing On-Chip Termination Channel bonding AC & DC Coupling



Virtex-4 Capabilities

- Any type of design runs at >400 MHz
- Pipelining provides extra performance "for free"
- Synchronous is best, but 32 clock are available
- Gigabit serial saves pins and board area
- On-chip termination for board signal integrity
- I/O features support double-data rate operation and source-synchronous design

Details available now, after Virtex-4 official introduction



Virtex-4 Capabilities

 Popular functions are hard-wired for lower cost, higher performance, and ease-of-use: microprocessors, FIFOs, serial I/O, clock management, etc.

- Many pre-tested soft cores are available Some are free, some for a fee
- One-hot state machines are preferred But MicroBlaze and PicoBlaze may be better
- Massive parallelism enhances DSP, Up to 1024 fast two's complement multipliers per chip, faster than dedicated DSP chips, but needs system-rethinking



2004 Challenges Technology moves rapidly: 130, 90, 65 nm Multiple Vcc, lower voltage - higher current Lower Vcc makes decoupling very critical Moore's law becomes more difficult to sustain Leakage current has increased significantly Triple-oxide transistors and clever design provide relief Signal integrity on pc-boards is crucial "homebrew" prototyping would waste money and time

Use Standard Evaluation Boards Instead

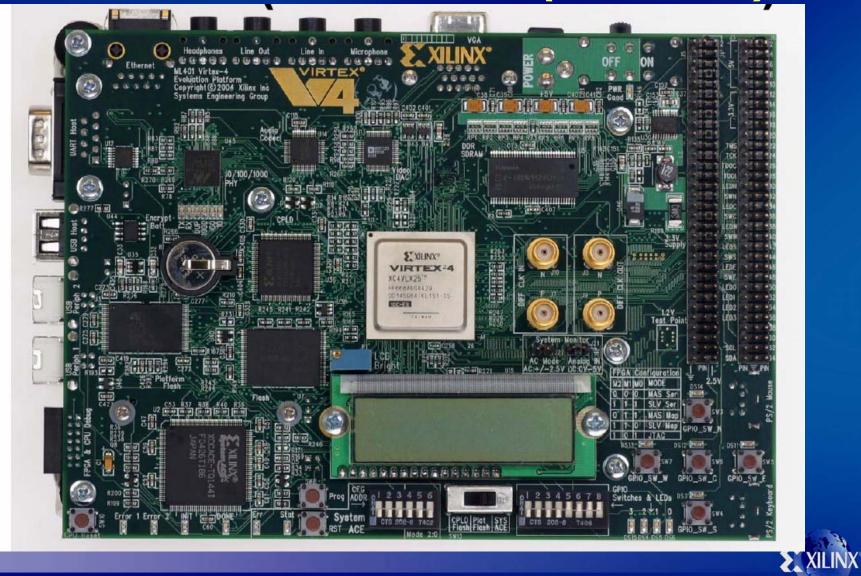


AFX Basic Evaluation Boards

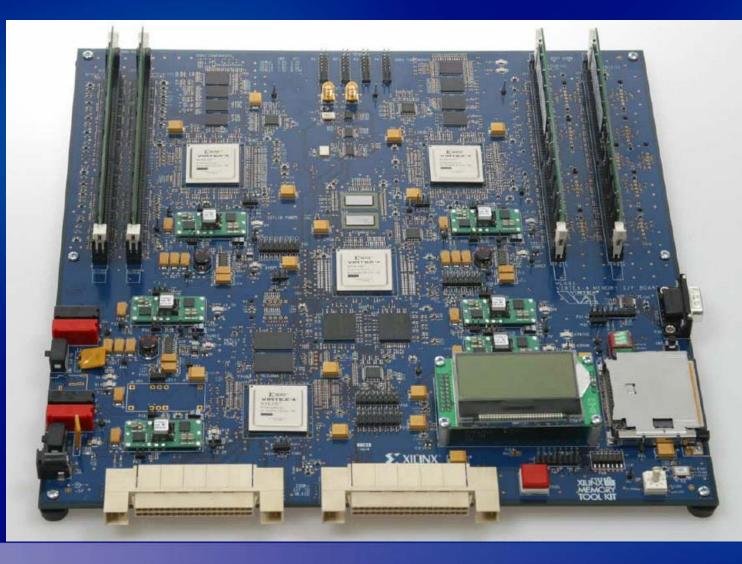


36 LHC Boston Sept 04 PA

Low-Cost ML40X (~ \$ 700)



ML46X- Memory Eval. Board



XILINX

ChipScope Pro for Real-Time Debug

- Debugging usually dominates the design effort
 - needs access to chip-internal nodes and busses
 - practically impossible to dedicate extra pins and routing
 - don't waste time "debugging the debugger"
- ChipScope Pro has internal virtual test headers
 - Small cores that act as internal logic state analyzers
- ChipScope Pro provides full visibility at speed
 - Read-out via JTAG, no extra pins needed

ChipScope Pro is the best tool for logic debugging



ChipScope Pro Available Today





ChipScope Pro on-chip debug solution 60-Day free evaluation version \$695 full version www.xilinx.com/chipscope

Agilent FPGA Dynamic Probe

Purchased separately from Agilent Acquisition \$ 995 option for your 16900, 1690 or 1680 logic analyzer www.agilent.com/find/FPGA



Agilent Technologies



1 Hz to 640 MHz Pulse Generator

Direct Digital Synthesis in smallest Spartan3 chip

- PicoBlaze for arithmetic and user interface
- Special DCM frequency synthesis for <350 ps jitter
- External PLL for jitter reduction to 100 picoseconds
- Max 640 MHz in 1 Hz steps, 1 ppm accuracy
- Three SMA outputs: LVDS plus single-ended
 - 1000 frequency values can be stored in EEPROM
- Small size, low cost, easy single-knob control Early 2005, next generation will reach 5 GHz



640 MHz Pulse Generator





Two Problems and Solutions

Single-Event Upsets (SEUs) radiation-induced soft errors

and

Extra Metastable Delay

unpredictable delay when set-up time is violated



Single-Event Upsets in Virtex-II SEU = random soft error, directly or indirectly caused by solar radiation Known problem at high altitude and space traditionally not a problem at sea level. Many tests, papers, show ways to mitigate: readback, scrubbing, triple redundancy Aerospace apps tolerate the cost/size penalty.

Creates FUD: Fear, Uncertainty & Doubt



Radiation Sources

Galactic Cosmic Rays (GCRs)

Solar Protons

Heavier lons

Trapped Particles

Protons, Electrons, Heavy lons

Nikkei Science, Inc. of Japan, by K. Endo, Prof. Yohsuke Kamide



Traditional Test Methods

Vastly accelerated testing procedures bombarding operating FPGAs at Los Alamos and Sandia Labs Many SEUs are detected and reported But:

There is no agreed-upon conversion factor to "normal" terrestrial operation.

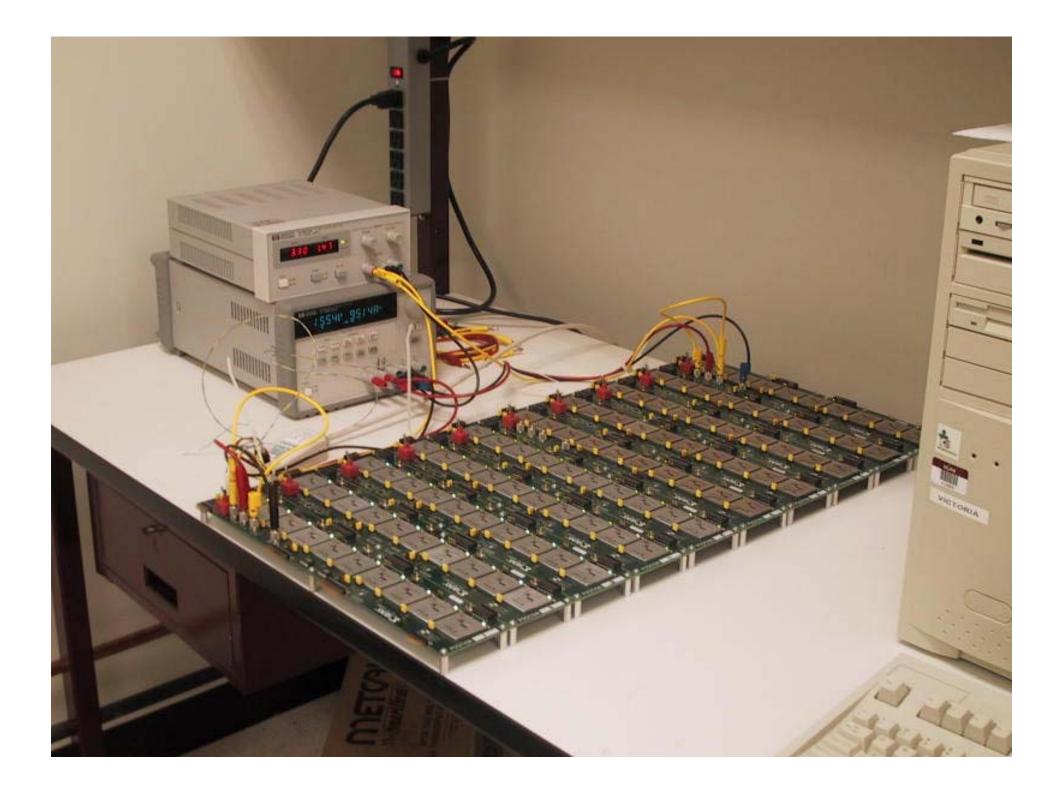
... there really was no meaningful data



Xilinx Large-Scale Test

4 boards with 100 XC2V6000s each Running 24 hrs/day, internet-monitored readback and error logging 24 times/day San Jose, (at sea level) Albuquerque, NM (1500 m elevation) White Mountain, CA (4000 m) Mauna Kea, Hawaii, (4000 m)





What's the Real MTBF ?

Measured mean time between SEUs in XC2V6000 at sea level is **18 to 23 years** (with 95% confidence.) But >90% of config. cells are always unused, The Real Mean Time Between Functional Failure therefore is **180 to 230 years** for XC2V6000 or **1300 years MTBFF for XC2V1000**

90-nm has been tested to be 15% better yet !



Metastability

Violating set-up time can cause **unknown delay** A potential problem for **all** asynchronous circuits Problem is statistical and **cannot be "solved"** Xilinx published tests in 1988, 1996, and 2001 Modern CMOS flip-flops recover surprisingly fast

Metastability is now irrelevant in many cases



Metastability Capture Window

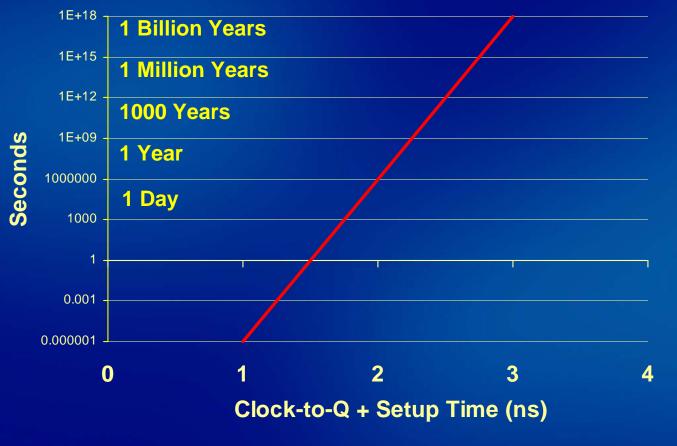
Tested on Virtex-IIPro

- 0.07 nanoseconds for a 1 ns delay clk-to-Q+set-up
- 0.07 femtoseconds for a 1.5 ns delay
- etc

A million times smaller for each additional 0.5 ns of delay This parameter is independent of clock and data rates

Makes it easy to calculate MTBF in any system

Mean-Time-Between-Failure as a Function of Tolerable Delay



at 300 MHz clock rate and ~50 MHz data rate



FPGAs have become

cheaper faster bigger more versatile and easier to use

They are now the obvious first choice for the system designer Thank you for your attention !

